

# LNJ808R88RA

## Ultra High Bright Surface Mounting Chip LED

InGaAlP SS Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	50	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +100	$^\circ\text{C}$

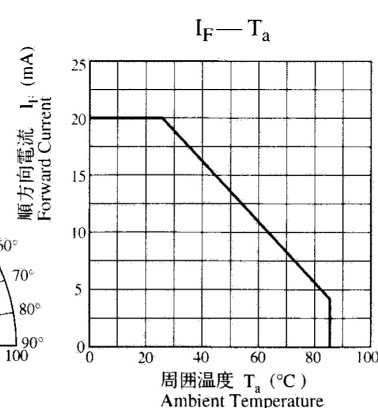
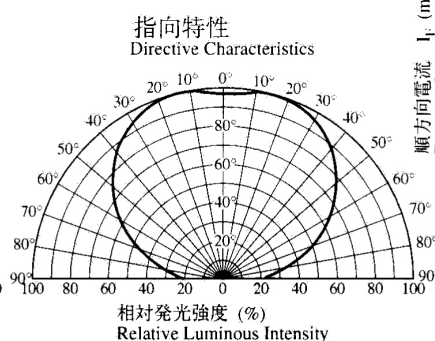
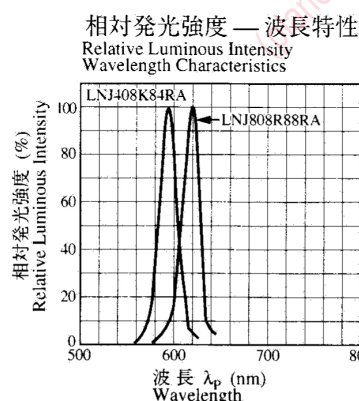
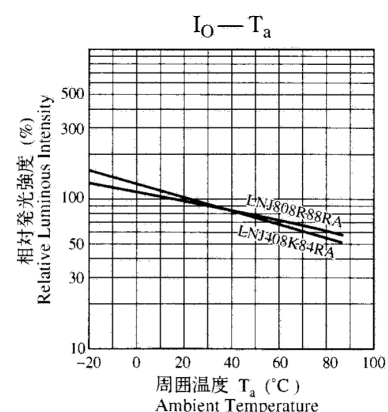
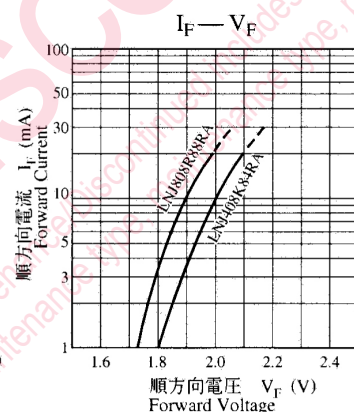
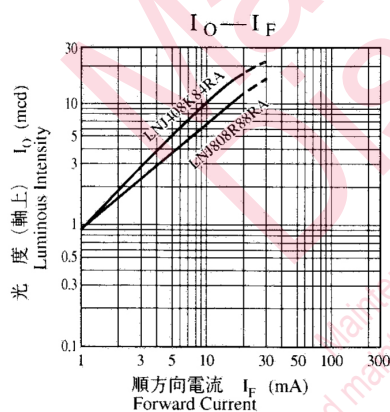
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

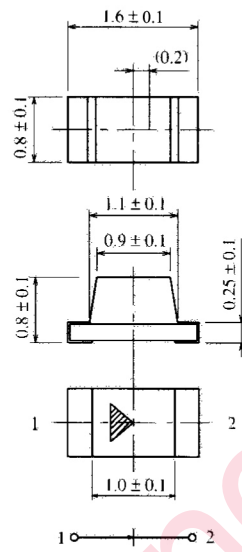
- Orange / Red Diffused

■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		2.5	6.5		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.9	2.3	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		620		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		17		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$



## ■ Package (Unit: mm)



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.  
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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